

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-4. (canceled)

5. (currently amended) ~~The IC chip package as claimed in claim 4~~ An IC chip package comprising: a substrate having a top side, a bottom side, and a plurality of conductive pads arranged on the top side;

a chip fixedly mounted on the top side of said substrate and having a plurality of conductive pads;

a plurality of bonding wires respectively electrically connected between the conductive pads of said substrate and the conductive pads of said chip;

adhesive means provided on the top side of said substrate around the border thereof;

a cover adapted for covering said substrate; and

a spacer connected between said substrate and said cover to keep said cover from said substrate at a distance, wherein said spacer comprises at least one column respectively fixedly connected between said substrate and said cover, and wherein the top side of said substrate has at least one recessed locating hole adapted to receive said at least one column.

6. (currently amended) ~~The IC chip package as claimed in claim 4~~ An IC chip package comprising: a substrate having a top side, a bottom side, and a plurality of conductive pads arranged on the top side;

a chip fixedly mounted on the top side of said substrate
and having a plurality of conductive pads;

a plurality of bonding wires respectively electrically
connected between the conductive pads of said substrate and
the conductive pads of said chip;

adhesive means provided on the top side of said substrate
around the border thereof;

a cover adapted for covering said substrate; and

a spacer connected between said substrate and said cover
to keep said cover from said substrate at a distance,
wherein said spacer comprises at least one column respectively
fixedly connected between said substrate and said cover, and
wherein said substrate comprises at least one locating through
hole extended through the top and bottom sides thereof, and
the at least one column of said spacer is respectively
inserted through the at least one locating hole of said
substrate and exposed to the outside of the bottom side of
said substrate.

7-8.(cancelled)

9.(currently amended)~~The IC chip package as claimed in claim~~
~~1~~ An IC chip package comprising: a substrate having a top
side, a bottom side, and a plurality of conductive pads
arranged on the top side;

a chip fixedly mounted on the top side of said substrate
and having a plurality of conductive pads;

a plurality of bonding wires respectively electrically
connected between the conductive pads of said substrate and
the conductive pads of said chip;

adhesive means provided on the top side of said substrate
around the border thereof;

a cover adapted for covering said substrate; and
a spacer connected between said substrate and said cover
to keep said cover from said substrate at a distance,
wherein said cover is made of transparent material.

10. (currently amended) ~~The IC chip package as claimed in claim~~

± An IC chip package comprising: a substrate having a top
side, a bottom side, and a plurality of conductive pads
arranged on the top side;

a chip fixedly mounted on the top side of said substrate
and having a plurality of conductive pads;

a plurality of bonding wires respectively electrically
connected between the conductive pads of said substrate and
the conductive pads of said chip;

adhesive means provided on the top side of said substrate
around the border thereof;

a cover adapted for covering said substrate; and

a spacer connected between said substrate and said cover
to keep said cover from said substrate at a distance,
wherein said cover has a through hole aimed at said chip, and
at least one lens respectively sealed in the through hole.

11. (currently amended) ~~The IC chip package as claimed in claim~~

± An IC chip package comprising: a substrate having a top
side, a bottom side, and a plurality of conductive pads
arranged on the top side;

a chip fixedly mounted on the top side of said substrate
and having a plurality of conductive pads;

a plurality of bonding wires respectively electrically
connected between the conductive pads of said substrate and
the conductive pads of said chip;

adhesive means provided on the top side of said substrate around the border thereof;

a cover adapted for covering said substrate; and

a spacer connected between said substrate and said cover to keep said cover from said substrate at a distance.,

wherein said cover comprises a screw hole extended through the top and bottom sides thereof corresponding in location to said chip, and a lens unit mounted in said screw hole, said lens unit comprising a barrel threaded into said screw hole and at least one lens sealed in said barrel.

12-18. (canceled)

19. (currently amended) ~~The IC chip package as claimed in claim 16~~ An IC chip package comprising: a substrate having a top side, a bottom side, and a plurality of conductive pads arranged on the top side;

a chip fixedly mounted on the top side of said substrate and having a plurality of conductive pads;

a plurality of bonding wires respectively electrically connected between the conductive pads of said substrate and the conductive pads of said chip;

adhesive means provided on the top side of said substrate around the border thereof;

a cover adapted for covering said substrate; and

a spacer connected between said substrate and said cover to keep said cover from said substrate at a distance, wherein said package further comprises a connecting device adapted to electrically connect the conductive pads of said

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substrate to an external object outside said substrate, and
wherein said connecting device comprises a plurality of metal
leads, said metal leads each having one end electrically
connected to the conductive pads at the top side of said
substrate and an opposite end extended to the outside of said
substrate and bent into a predetermined shape.